

Revision 20231109

LNPTM STAT-KONTM COMPOUND AE004

AC-1004 REGION AMERICAS

DESCRIPTION

LNP STAT-KON AE004 compound is based on Acrylonitrile Butadiene Styrene (ABS) resin containing 20% carbon fiber. Added features of this grade include: Electrically Conductive.

GENERAL INFORMATION	
Features	Electrically Conductive, Carbon fiber filled, High stiffness/Strength, No PFAS intentionally added
Fillers	Carbon Fiber
Polymer Types	Acrylonitrile Butadiene Styrene (ABS)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components
Industrial	Material Handling

TYPICAL PROPERTY VALUES

PROPERTIES UNITS **TEST METHODS TYPICAL VALUES** MECHANICAL⁽¹⁾ Tensile Stress, brk, Type I, 5 mm/min 95 MPa ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 2.6 % ASTM D638 Tensile Modulus, 50 mm/min 12960 MPa ASTM D638 Flexural Stress, brk, 1.3 mm/min, 50 mm span 131 MPa ASTM D790 10610 ASTM D790 Flexural Modulus, 1.3 mm/min, 50 mm span MPa Tensile Stress, break, 5 mm/min 90 MPa ISO 527 Tensile Strain, break, 5 mm/min 2.3 % ISO 527 ISO 178 Flexural Stress 152 MPa 12750 ISO 178 Flexural Modulus, 2 mm/min MPa IMPACT (1) Izod Impact, unnotched, 23°C 320 ASTM D4812 J/m Izod Impact, notched, 23°C ASTM D256 60 J/m Izod Impact, unnotched 80*10*4 +23°C 16 ISO 180/1U kJ/m² Izod Impact, notched 80*10*4 +23°C 6 kJ/m² ISO 180/1A THERMAL⁽¹⁾ °C HDT, 1.82 MPa, 3.2mm, unannealed 100 ASTM D648 CTF. -30°C to 30°C, flow 2.0E-05 1/°C ASTM D696 CTE, -30°C to 30°C, xflow 7.2E-05 1/°C ASTM D696 °C HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm 105 ISO 75/Bf HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm 100 °C ISO 75/Af PHYSICAL (1)

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CHEMISTRY THAT MATTERS



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Specific Gravity	1.14		ASTM D792
Density	1.14	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.25	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.1 – 0.3	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.3 – 0.6	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	0.25	%	ISO 62
ELECTRICAL ⁽¹⁾			
Surface Resistivity ⁽³⁾	1.E+02 – 1.E+04	Ω	ASTM D257
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05 – 0.1	%	
Melt Temperature	260	°C	
Front - Zone 3 Temperature	265 – 275	°C	
Middle - Zone 2 Temperature	230 – 245	°C	
Rear - Zone 1 Temperature	205 – 215	°C	
Mold Temperature	70 – 80	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Measurement meets requirements as specified in ASTM D4496.

(4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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